

## Product Change Notification / LIAL-23USLU235

# Date:

12-Oct-2020

# **Product Category:**

8-bit Microcontrollers, Interface- Controller Area Network (CAN), Interface- Serial Peripherals

# PCN Type:

Manufacturing Change

## **Notification Subject:**

CCB 3979 and 3979.001 Initial Notice: Qualification of QMI-519 die attach material for selected products available in 28L SOIC (.300in) and 18L SOIC (.300in) packages at MTAI assembly site

## Affected CPNs:

LIAL-23USLU235\_Affected\_CPN\_10122020.pdf LIAL-23USLU235\_Affected\_CPN\_10122020.csv

# **Notification Text:**

PCN Status: Initial notification.

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the icons found in the Affected CPNs section

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .csv).

**Description of Change:** Qualification of QMI-519 die attach material for selected products available in 28L SOIC (.300in) and 18L SOIC (.300in) packages at MTAI assembly site

**Pre Change:** Using 3280 die attach material

#### Post Change:

#### Using QMI-519 die attach material

#### Pre and Post Change Summary:

	Pre Change	Post Change			
Assembly Site	Microchip Technology Thailand	Microchip Technology Thailand			
	(MTAI)	(MTAI)			
Wire material	CuPdAu	CuPdAu			
Die attach material	3280	QMI-519			
Molding compound material	G600	G600			
Lead frame material	C194	C194			

#### Impacts to Data Sheet: None

#### Change Impact:None

**Reason for Change:**To improve productivity by qualifyingQMI-519 die attach material

#### Change Implementation Status: In Progress

#### Estimated Qualification Completion Date:

November 2020

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

#### Time Table Summary:

	October 2020					November 2020				
Workweek	40	41	42	43	44	45	46	47	48	49
Initial PCN Issue Date			Х							
Qual Report Availability										Х
Final PCN										Х

# Issue Date

#### Method to Identify Change: Traceability code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan

Revision History:October 12, 2020: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

# Attachments:

### PCN\_LIAL-23USLU235\_Qual Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

#### **Terms and Conditions:**

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. LIAL-23USLU235 - CCB 3979 and 3979.001 Initial Notice: Qualification of QMI-519 die attach material for selected products available in 28L SOIC (.300in) and 18L SOIC (.300in) packages at MTAI assembly site

Affected Catalog Part Numbers (CPN)

PIC16CR54CT-20/SO012 CF745-04/SO PIC16LC54C-04/SO PIC16C54C-04/SO PIC16C54C-20/SO PIC16C54C-40/SO PIC16C54C-04/SOC04 PIC16C54C-20E/SO PIC16LC54C-04I/SO PIC16C54C-04I/SO PIC16C54C-20I/SO PIC16C54CT-20/SO068 PIC16LC54CT-04/SO150 PIC16C54CT-04/SO PIC16C54CT-04I/SO104 PIC16C54CT-04I/SO MCP23008-E/SO MCP23008T-E/SO MCP23S08-E/SO MCP23S08T-E/SO MCP23017-E/SO MCP23017T-E/SO MCP23S17-E/SO MCP23S17T-E/SO MCP2515-E/SO MCP2515-E/SORB2 MCP2515-E/SORB4 MCP2515-I/SO MCP2515-I/SORB2 MCP2515-I/SORB4 MCP2515T-I/SO MCP2515T-I/SORB2 MCP2515T-I/SORB4 MCP2515T-E/SO MCP2515T-E/SORB2 MCP2515T-E/SORB4 PIC16F54-E/SO PIC16F54-I/SO023 PIC16F54-I/SO043 PIC16F54-I/SO PIC16F54T-I/SO036 PIC16F54T-I/SO042 PIC16F54T-I/SO043 PIC16F54T-I/SO PIC16F54T-E/SO040 PIC16F57-E/SO

LIAL-23USLU235 - CCB 3979 and 3979.001 Initial Notice: Qualification of QMI-519 die attach material for selected products available in 28L SOIC (.300in) and 18L SOIC (.300in) packages at MTAI assembly site

PIC16F57-I/SO MCV28A-I/SO PIC16F57T-I/SO028 PIC16F57T-I/SO PIC16F57T-E/SO PIC16F570-I/SO PIC16F716-E/SO PIC16F716-I/SO PIC16F716T-I/SO048 PIC16F716T-I/SO061 PIC16F716T-I/SO PIC16F716T-E/SO MCP23018-E/SO MCP23018T-E/SO MCP23S18-E/SO MCP23S18T-E/SO PIC16LF1902-I/SO PIC16LF1903-I/SO PIC16F723A-E/SO PIC16F723A-I/SO PIC16F723AT-I/SO PIC16F722A-E/SO PIC16F722A-I/SO PIC16F722AT-I/SO PIC16LF723A-E/SO PIC16LF723A-I/SO PIC16LF722A-E/SO PIC16LF722A-I/SO